

**AMENDMENTS TO THE CLAIMS**

Pursuant to 37 C.F.R. § 1.121 the following listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Previously Presented): A semiconductor device, comprising:

a semiconductor element with an area for a main surface of  $1 \text{ mm}^2$  or greater;

a substrate having a thermal conductivity of  $170 \text{ W/m-K}$  or greater and having an upper surface on which said element is mounted and a bottom surface which is positioned on the opposite side; and

a ratio  $H/L$  being greater than or equal to 0.3 but less than 1.25, with  $L$  being the length in the long direction of a main surface of said semiconductor element, and  $H$  being the distance from a semiconductor element mounting part on said upper surface of said substrate to said bottom surface.

2. - 3. (Canceled)

4. (Previously Presented) The semiconductor device according to claim 1, further comprising:

a ratio of  $Y/L$  being equal to or greater than 2, with  $Y$  being the distance from one end of the bottom surface of the substrate to the opposite end of the bottom surface of the substrate along the same plane as  $L$ .

5. (Previously Presented) The semiconductor device according to claim 1, wherein the thermal conductivity of the substrate is equal to or greater than  $200 \text{ W/m-K}$ .



